



반도체 테스트 부문
Total Solution Provider

INVESTOR RELATIONS MAY 2025

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Semiconductor Testing
Total Solution Provider

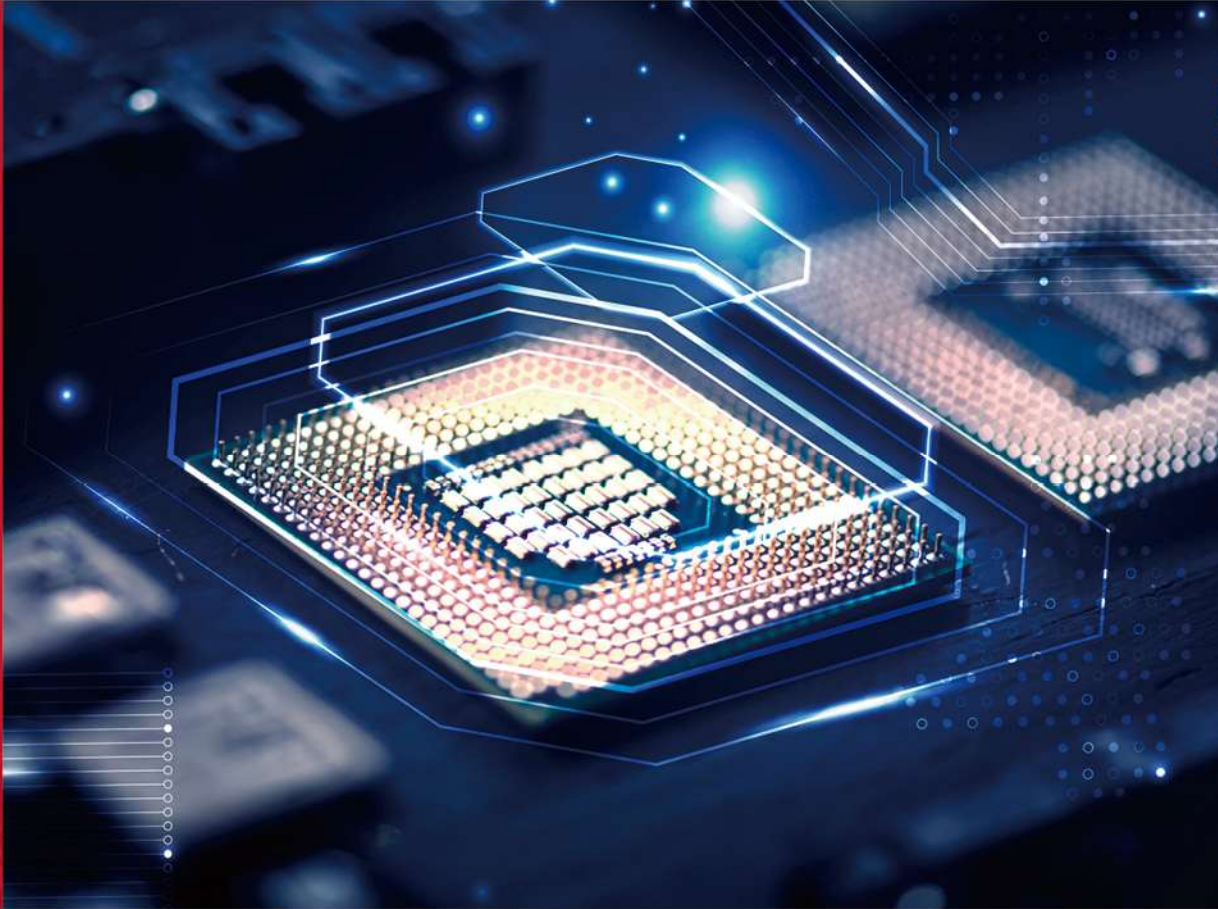


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Semiconductor Test
Total Solution Provider



01

**TFE,
Total Solution
Provider!**

01 Company Overview

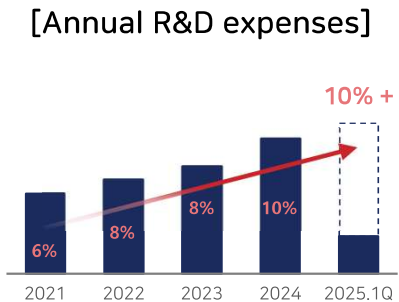
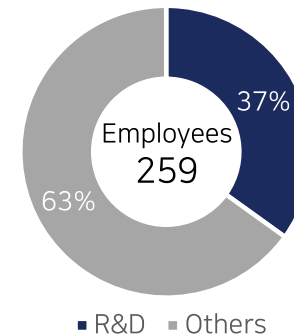
Total Solution Provider in Semiconductor Test Field

Company Overview

Company	TFE Co., Ltd
CEO	SJ. Moon
Establishment	2003. 10. 29
Capital	KRW 1.138 billion
Employees	259 (R&D 97)
Business Site	Gyeonggi-do, 18384, Republic of Korea
Website	www.tfe.co.kr

R&D Innovation Framework

Three R&D Centers

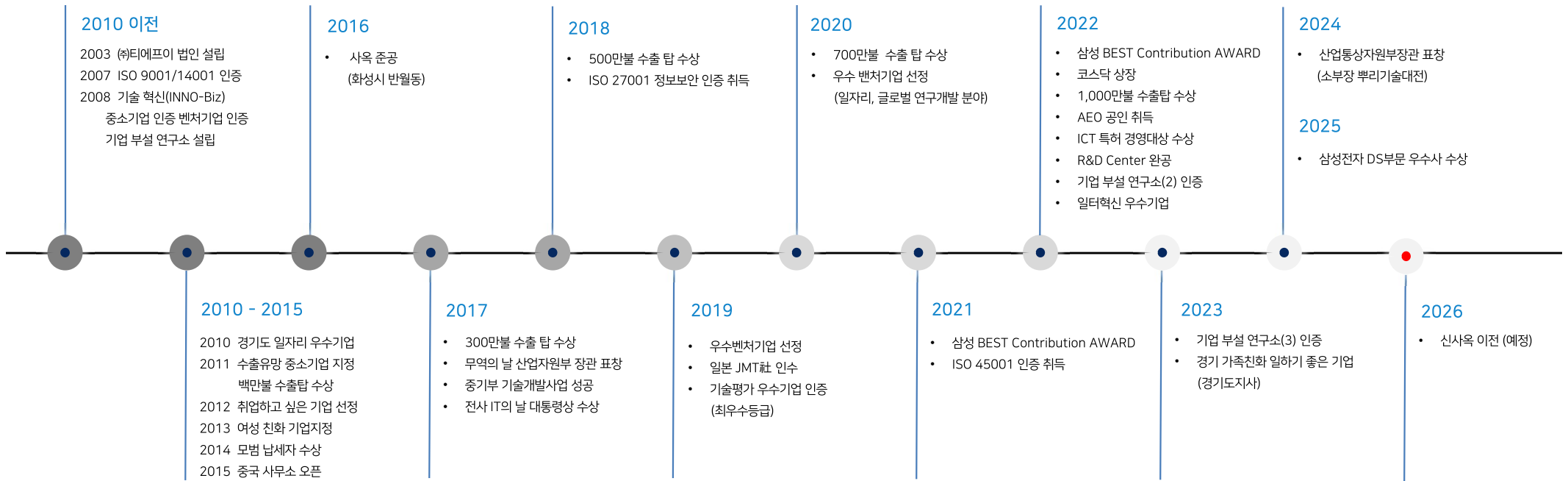


Patent and intellectual property status

Test Socket	Board	COK
31	26	56

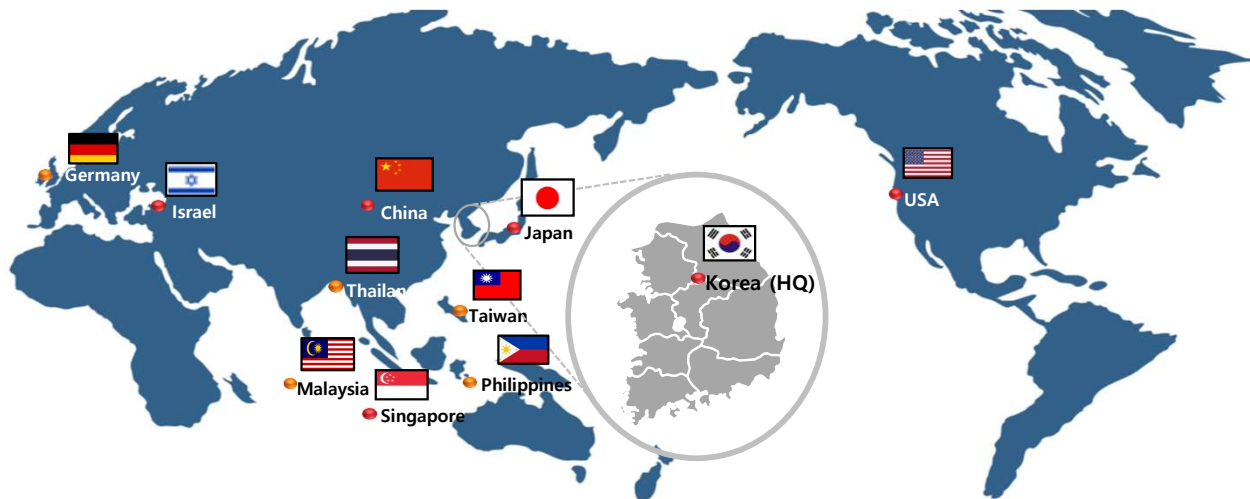
02 Corporate History

Proving Innovation, Sustaining Excellence



03 Infra – All over the World

Global Infrastructure, Local Commitment



- 01 Planning new branch in USA & Singapore
- ✓ Total 3 Local Staffs on duty
 - ✓ Actively targeting the USA & SG market, the headquarters of many global customers

- 02 Agency, a solid partners
- ✓ USA, Taiwan, Israel, Singapore, etc.
 - ✓ Continuous searching for partners

- 03 Exhibitions
- ✓ 4 exhibitions scheduled for 2025
 - ✓ TestConX(USA), Semi SEA(Singapore), Taiwan, USA, Japan



04 Product Portfolio

One-Stop Solution for Global Chipmakers' Economic Benefits

Test Socket

[Memory]

[Non-Memory]

Electrical connection between test board and chip

Board

[Test Board]

[Burn-in Board]

Conduct electrical connection

High/Low temperature test

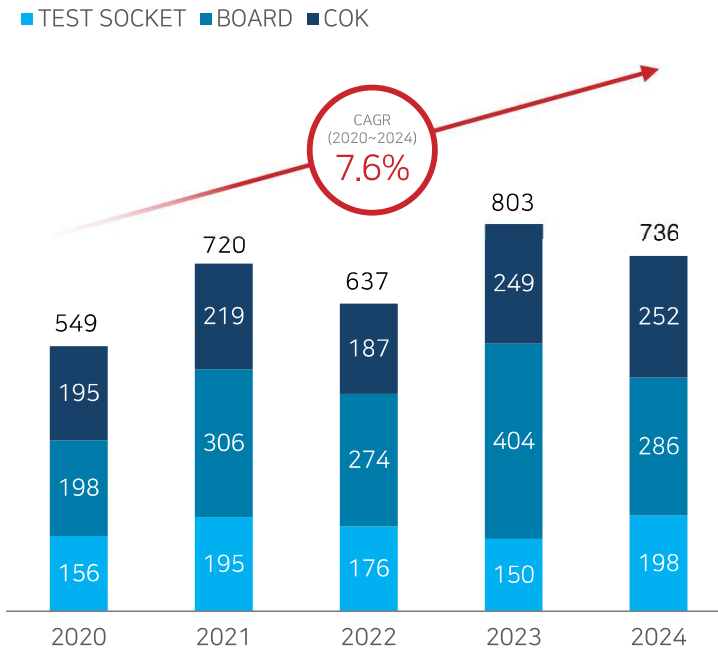
COK

[Memory]

[Non-Memory]

Transfer chips & Support connectivity for inspection

Sales trends by Product (Unit: KRW 100 million)

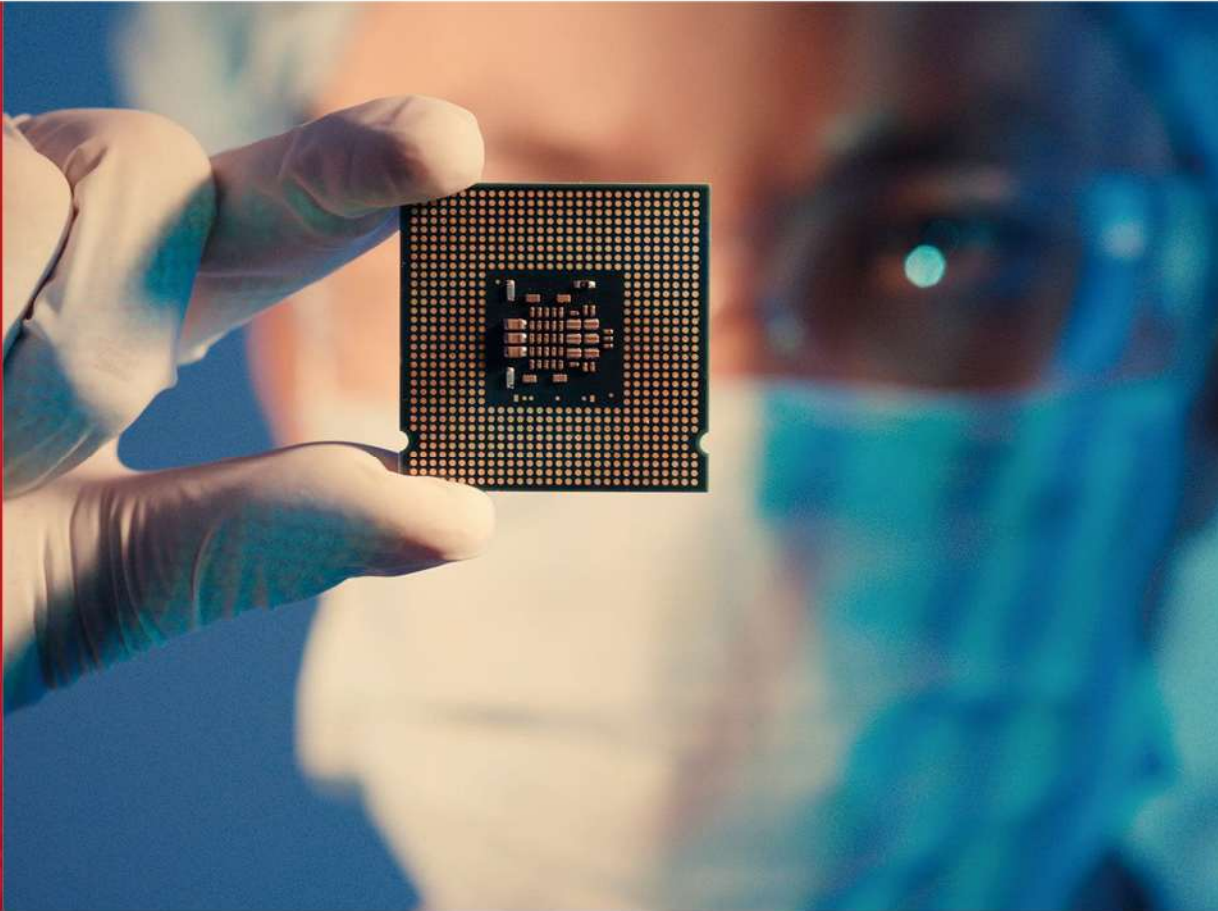


※ Consolidated Financial Statements Basis

3 : 4 : 3

02

Business Performance



Semiconductor Test
Total Solution Provider

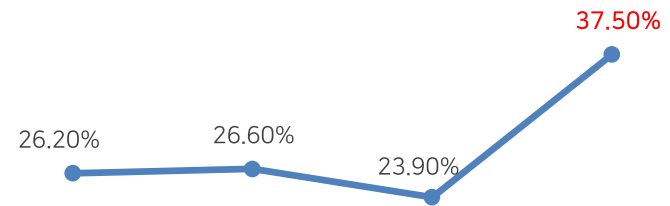
01 Business Performance

YoY 27%↑

2025. 1Q Sales **22.0** Billion won

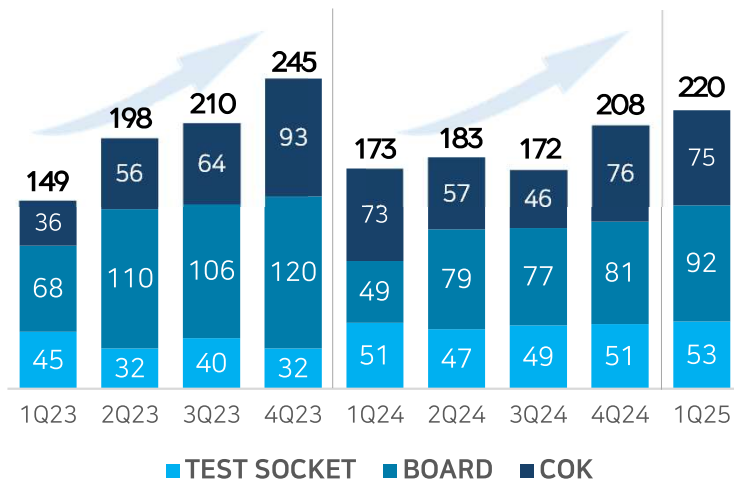
※Consolidated Financial Statements Basis

Export Revenue % (2022~2025.1Q)



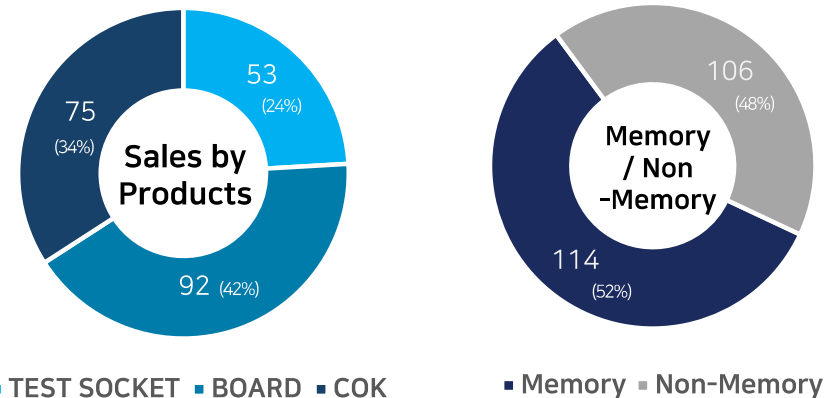
Quarterly Sales Status (2023~2025.1Q)

(Unit: KRW 100 million)



Sales Status by Products (2025.1Q)

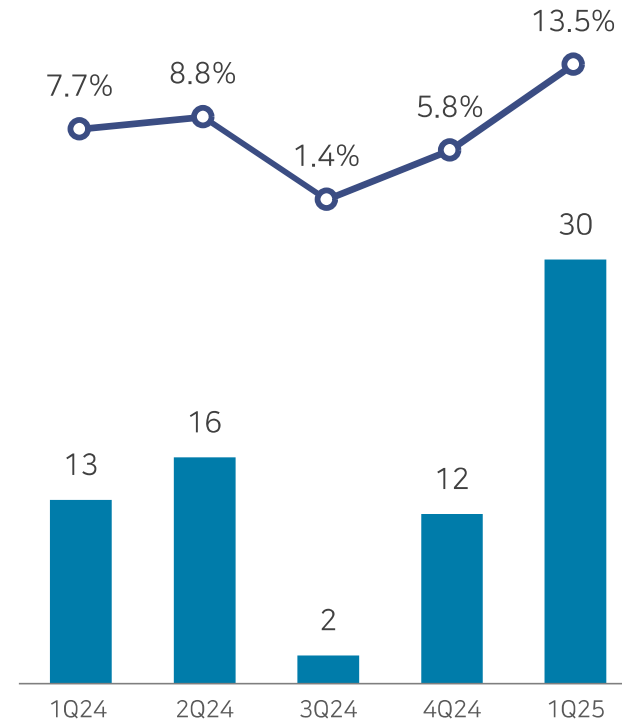
(Unit: KRW 100 million)



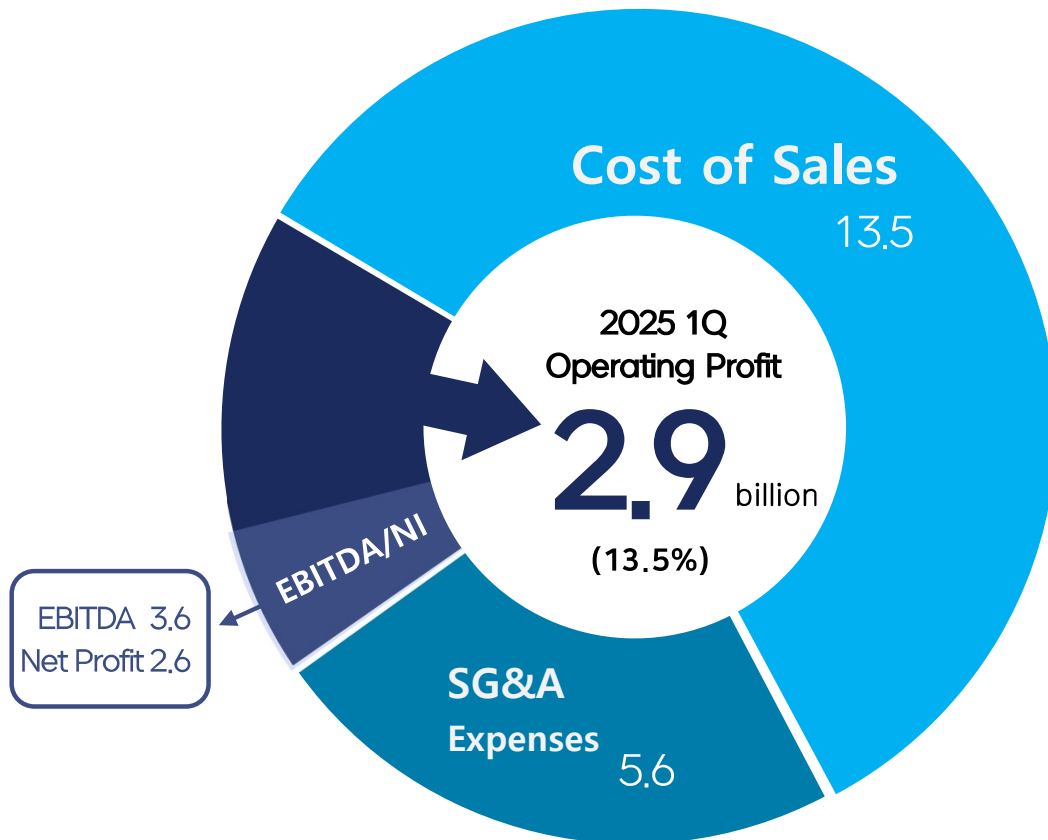
Solid Q1 Signals Another Promising Year

Quarterly Operating Profit Status (2024~2025.1Q)

(Unit: KRW 100 million, %)



※ Consolidated Financial Statements Basis



※ Consolidated Financial Statements Basis

03 Business Performance



Well-Capitalized and Ready to Scale

(단위: 억원)

Assets		Liabilities	
총자산	1,316	총부채	504
유동자산	743	유동부채	169
현금성 자산 등	542	차입금	73
매출채권	87	비유동부채	335
⋮		전환사채	232
Equity			
총자본	812		
자본금	11		
자본잉여금 등	292		
⋮			
이익잉여금	509		
비유동자산	573		
유형자산	461		
⋮			

주요 경영지표

유동비율		부채비율	
24Y	25.1Q	24Y	25.1Q
468.5%	440.1%	61.6%	62.1%

당기순이익률		영업이익률	
24Y	25.1Q	24Y	25.1Q
2.0%	11.9%	6.0%	13.5%

- 24Y 전환사채평가 제외 시 당기순이익률 11.1%

Capex

(단위: 억원)

22Y	23Y	24Y	25.1Q
58	108	183	33

※ 연결 재무제표 기준



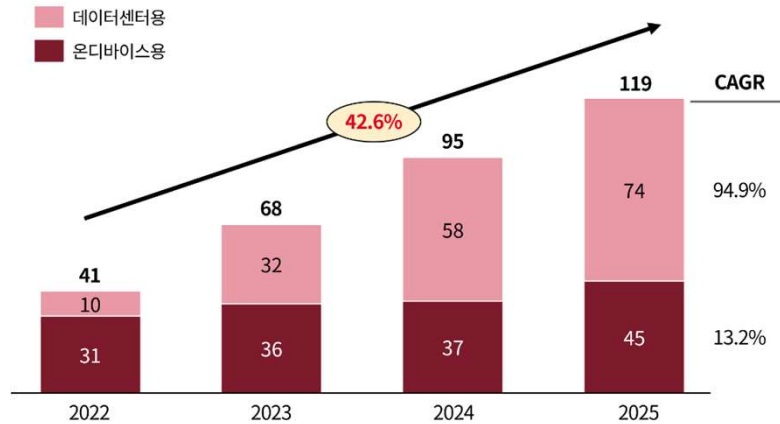
Semiconductor Test
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03

Growth Strategy

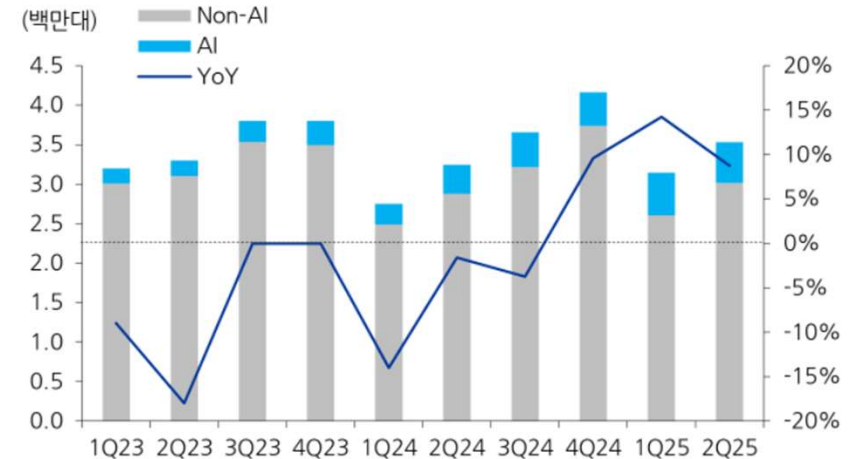
01 Market Insight

AI 반도체 시장 규모 변화 (단위: 십억 달러)



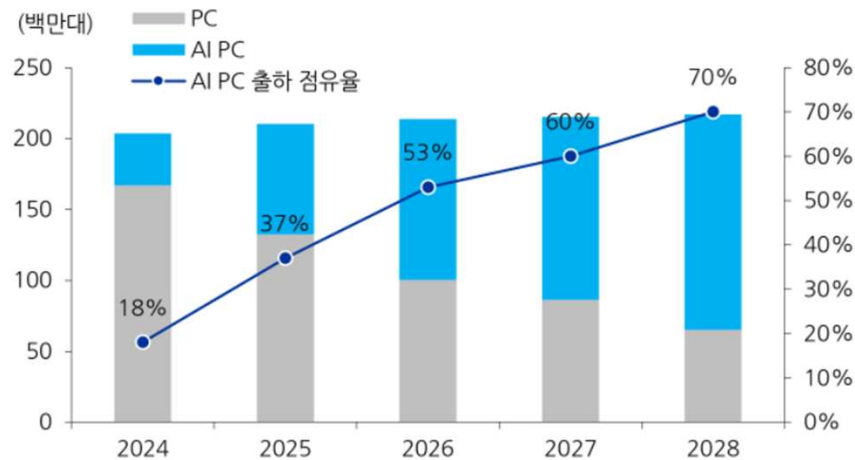
출처: Omdia, 한국수출입은행, PwC컨설팅 Insight April, 2025

서버 시장 전망과 YoY 추이



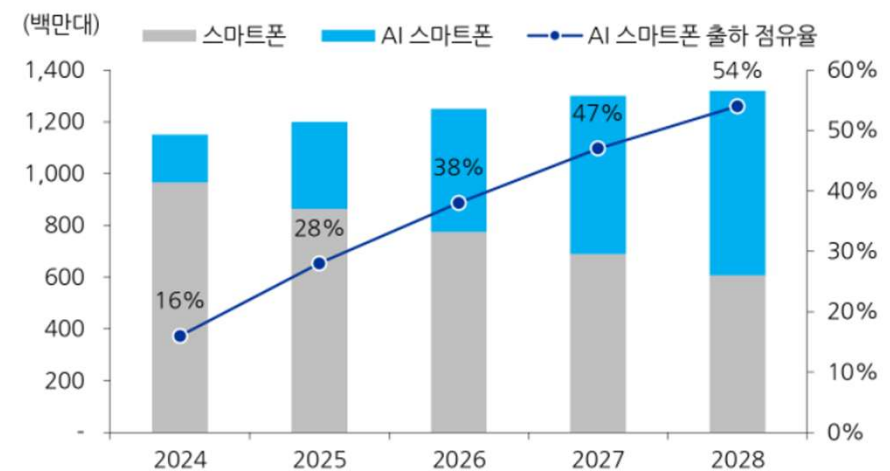
자료: 유진투자증권 추정치

데스크탑/노트북 출하량과 AI 제품 출하 점유율 전망



자료: 유진투자증권 추정치

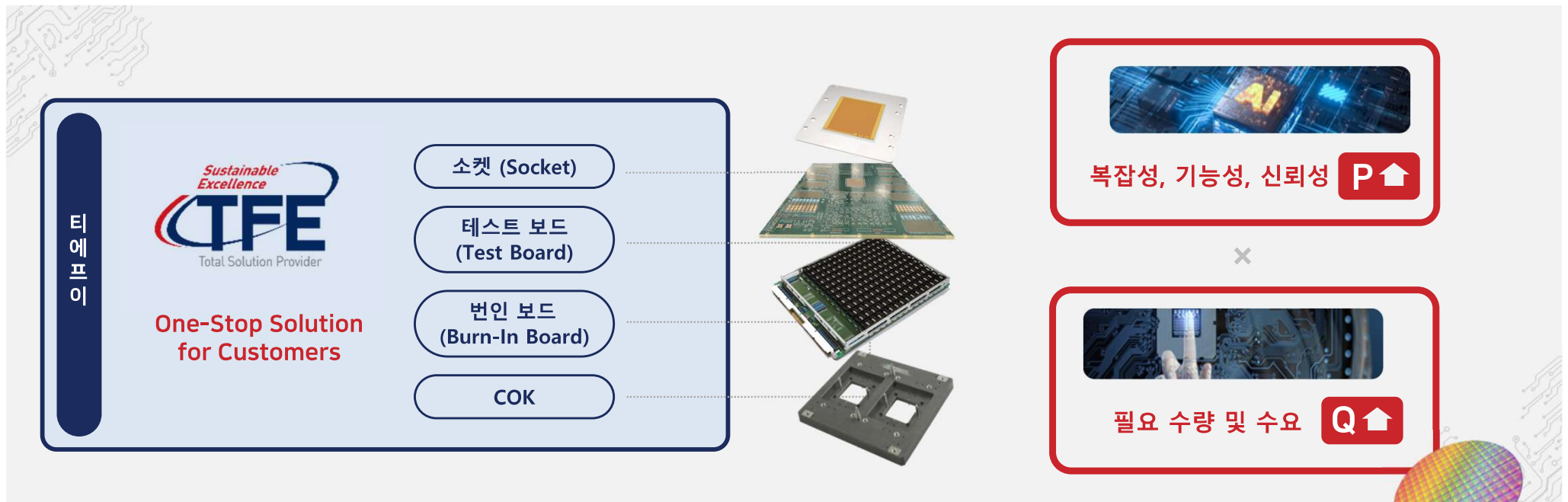
스마트폰 출하량과 AI 제품 출하 점유율 전망



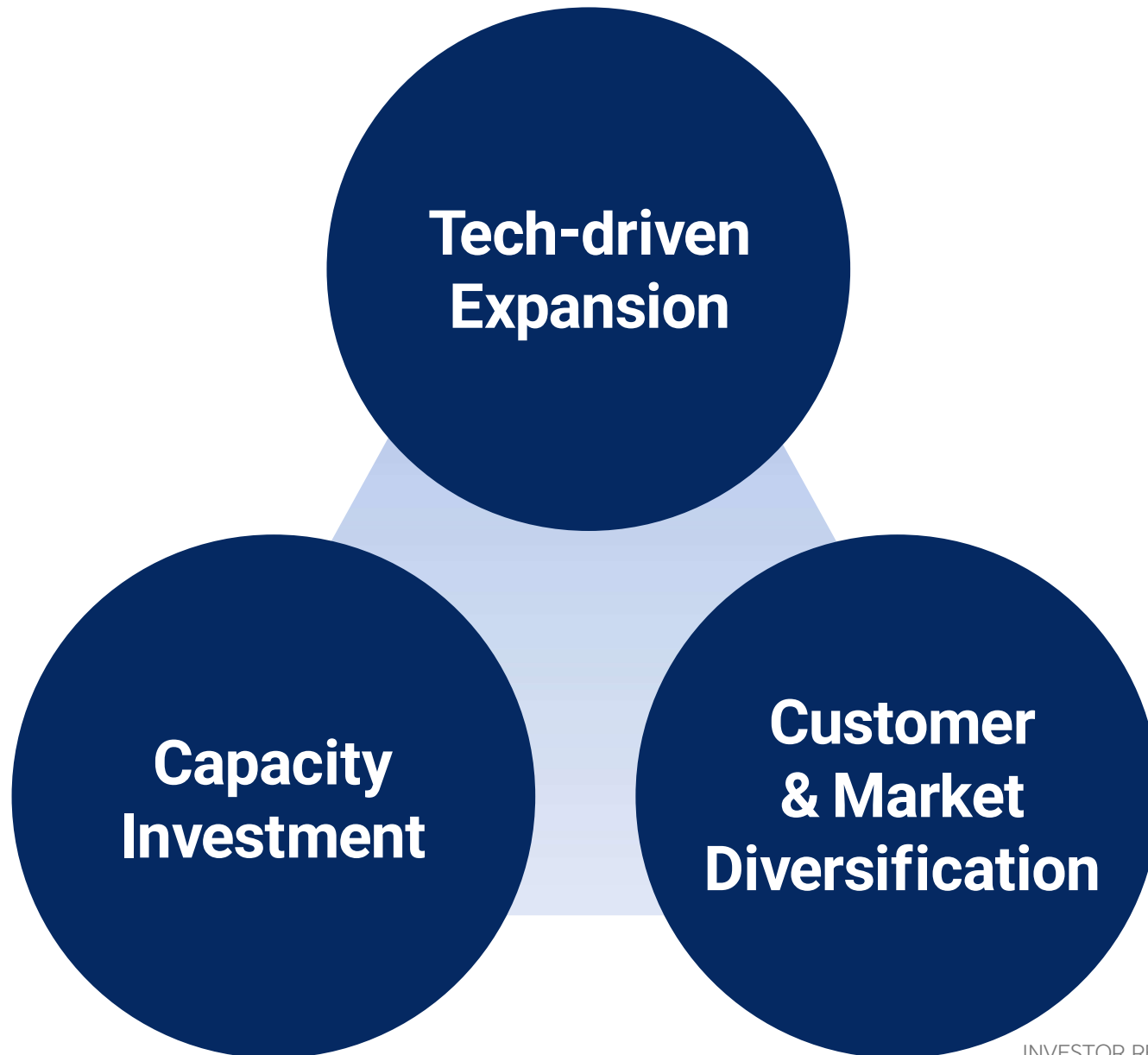
자료: 유진투자증권 추정치

02 One-Stop Solution - One & Only

Global No.1 Semiconductor Total Solution Provider



03 Growth Strategy – *Brave New World!*



TFE, Driving the Future Test Solution

AI(HBM, 2.5D)

DDR5 Module

Our Leadership Roadmap
Accelerated with 5 nodes in 4 years

Hybrid Disaggregated Ultra Low Power Performance

2021-2022	2023-2024	2024+
Alder Lake & Raptor Lake	Meteor Lake & Arrow Lake	Lunar Lake & Beyond
Intel 7	Intel 4, Intel 20A, Intel 18A	Intel 18A
Real World Performance	Leadership Compute, AI and Graphics	Performance per Watt Leadership

SOCAMM/LPCAMM (Next-Generation Module)

Flagship Smart Phone AP

Burn-in Test Socket

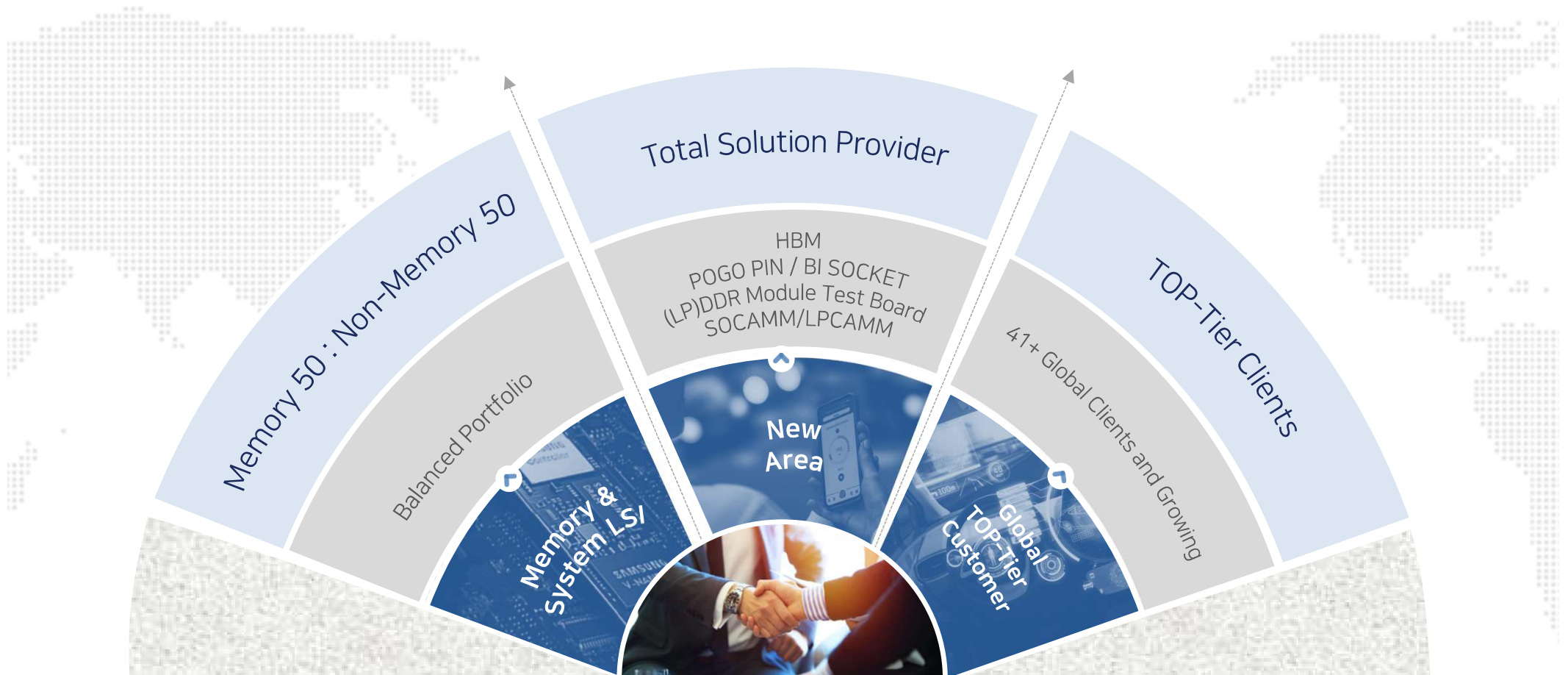
CXL CPO HBF Glass Substrate, Graphics Card

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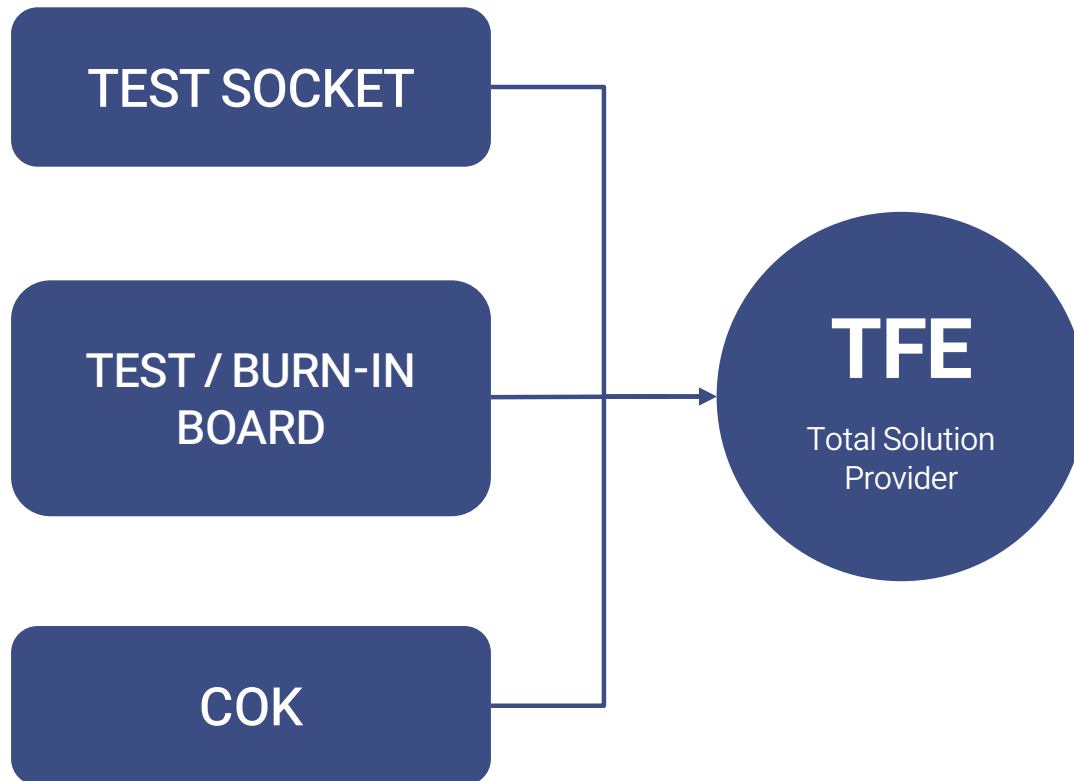
05 New Plant in 2026 – Higher Capacity & Automation



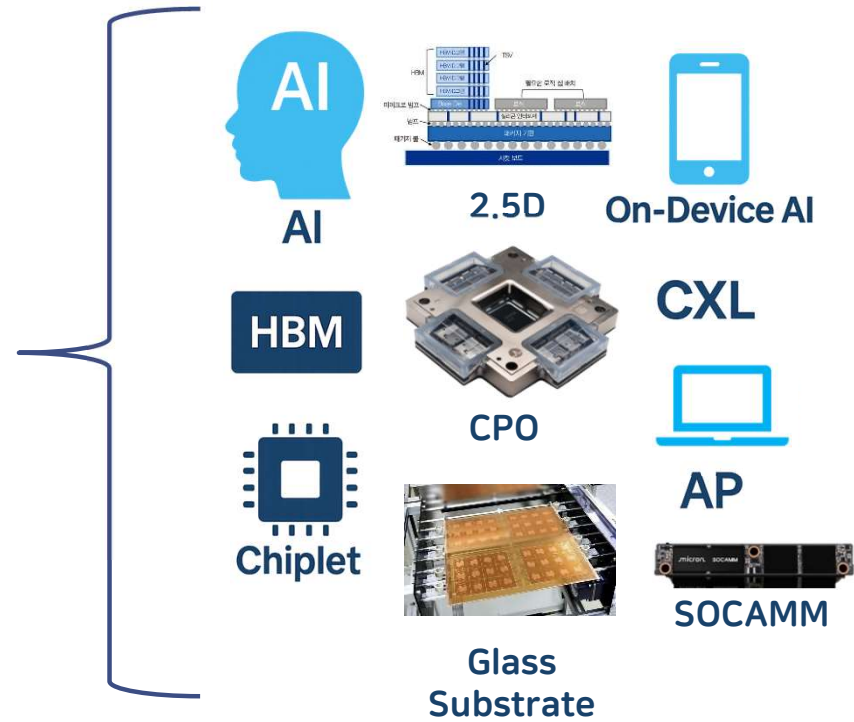
One & Only Test Partner for the Future



TEST COVERAGE



NEW-GEN TECHNOLOGIES





Appendix

01. Financial Statements Summary

01 Financial Statements Summary

요약 재무상태표

(단위: 억원)

구분	2025.1Q	2024	2023
유동자산	743	724	535
- 현금성자산	223	194	407
- 금융자산	319	372	-
- 채권·재고 등	201	158	128
비유동자산	573	543	379
자산총계	1,316	1,267	914
유동부채	169	155	144
비유동부채	335	328	58
※ 장단기차입금	75	76	68
부채총계	504	483	202
자본금	11	11	11
자본잉여금	241	240	240
기타자본항목	50	50	(8)
이익잉여금	510	483	469
자본총계	812	784	712

※ 연결 재무제표 기준

요약 손익계산서

(단위: 억원)

구분	2025.1Q	2024	2023
매출액	220	736	803
매출원가	135	503	536
매출총이익	85	233	267
판매관리비	55	189	175
영업이익	30	44	92
영업외수익	7	46	32
영업외비용	7	86	10
세전순이익	30	4	114
법인세비용	4	(11)	3
당기순이익	26	15	111